

**EPOXY RESIN COMPOSITION FOR SEMICONDUCTOR ENCAPSULATION
AND SEMICONDUCTOR DEVICE USING THE SAME**

ABSTRACT OF THE DISCLOSURE

The present invention relates to an epoxy resin composition for semiconductor encapsulation, including the following components (A) to (F): (A) an epoxy resin; (B) a
5 phenol resin; (C) a curing accelerator; (D) an inorganic filler; (E) a hydrotalcite compound; and (F) a carboxyl group-containing wax having an acid value of 10 to 100 mg KOH/g.

NO FIGURE